Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

CLAIMS 1 - 10 (CANCELLED).

11. (ORIGINAL) A thermally enhanced printed circuit (PC) wiring board for ball grid integrated circuit packages comprising a relatively thin, conductive metal core layer having oppositely facing surfaces and one or more holes in the metal core at each of a plurality of through-core via sites,

a first and second thin rigidifying non-conductive laminate sheet attached to said oppositely facing surfaces, respectively, and

at least one conductive circuit pattern on at least one of said thin rigidifying non-conductive sheets and a plurality of vias thereon.

12. (ORIGINAL) The PC wiring board defined in Claim 11 including a plurality of vias made by plating build-up and connecting to the core from both the top and bottom sides thereof.

13. (CURRENTLY AMENDED) The PC wiring board defined in Claim 11 wherein said conductive metal core layer is copper in the range of 5 - 15 mils ~~think~~ thick and said laminate sheets are fiberglass.

14. (ORIGINAL) The PC wiring board defined in Claim 13 including one or more additional non-conductive and conductive layers thereon.

15. (ORIGINAL) The PC wiring board defined in Claim 11 including a plurality of vias selected from Type 1, Type 2 or Type 3 vias as defined herein.

16. (ORIGINAL) The PC wiring board defined in Claim 12 including a plurality of vias selected from Type 1, Type 2 or Type 3 vias as defined herein.

17. (NEW) A thermally enhanced printed circuit (PC) wiring board for ball grid integrated circuit packages comprising:

a conductive metal core layer in the range of 5 - 15 mils thick and having oppositely facing surfaces and one or more holes in the metal core at each of a plurality of through-core via sites,

a first and second thin rigidifying non-conductive fiberglass laminate sheets attached to said oppositely facing surfaces of said conductive metal core layer, respectively,

at least one conductive circuit pattern on at least one of said thin rigidifying non-conductive sheets, and

a plurality of vias selected from type 1, type 2 or type 3 vias made by plating build-up and connecting to the core selectively from the top and bottom sides thereof, respectively.